Title: Qualification of STATS ChipPac as an additional assembly site for selected Devices Customer Contact: PCN Manager Dept: Quality Services Proposed 1st Ship Date: Oct 16, 2022 Sample Requests accepted until: Aug 19, 2022stample Requests received after Aug 18, 2022 will not be supported. Change Type: Design Wafer Bump Site Assembly Site Design Wafer Bump Site Assembly Materials Part number change Wafer Bump Material Assembly Materials Part number change Wafer Bump Material Assembly Materials Part number change Wafer Fab Materials Packing/Shipping/Labeling Test Process Wafer Fab Materials PCN Details Description of Change: Texas Instruments Incorporated is announcing the qualification of STATS ChipPac as an alternate Assembly site for devices listed below in the product affected section. There are no construction differences of the devices between the two assembly sites. Reason for Change: Supply continuity Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative): None Impact on Environmental Ratings Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. RoHS REACH Green Status IEC 62474 No Change No Change No Change No Change Changes to product identification resulting from this PCN: Assembly Site Assembly Site Origin (22L) Assembly Country Code (23L) Assembly City Amkor AMP KOR Gwangju STATS ChipPac SCK KOR INCHEON Sample product shipping label (not actual product label) TEXAS. INSTRUMENTS GA (21) 1, 2050-1981 (1P) SN74LS07NSR (21) 1, 2050-1981 (20) 2000 (D) 0336 (31T) LOT: 3959047MLA (4M) TKY(11T) 75224885312 (7) PREV: (7) 0033317 (20) 1, 2001 (EV) 1, 2001 (E											
Customer Contact: PCN Manager Dept: Quality Services	PCN Nu	PCN Number: 20220718001.1 PCN Date: July 19, 2022									
Proposed 1st Ship Date: *Sample requests received after Aug 18, 2022 will not be supported. *Sample requests received after Aug 18, 2022 will not be supported. Change Type: Assembly Site Design Wafer Bump Site Wafer Bump Material Wafer Bump Material Wafer Bump Material Wafer Bump Material Wafer Bump Process Data Sheet Wafer Bump Process Wafer Fab Site Wafer Fab Site Wafer Fab Site Wafer Fab Site Wafer Fab Materials Packing/Shipping/Labeling Test Site Wafer Fab Materials Wafer Fab Process Wafer Fab Process PCN Details Pescription of Change: Texas Instruments Incorporated is announcing the qualification of STATS ChipPac as an alternate Assembly site for devices listed below in the product affected section. There are no construction differences of the devices between the two assembly sites. Reason for Change: Supply continuity Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative): None Impact on Environmental Ratings Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. RoHS REACH Green Status IEC 62474 No Change No Change No Change No Change Changes to product identification resulting from this PCN: Assembly Site Assembly Site Origin (22L) Assembly Country Code (23L) Assembly City Amkor AMP KOR Gwangju STATS ChipPac SCK KOR INCHEON Sample product shipping label (not actual product label) TEXAS NATE ChipPac SCK (1P) \$N74LSO7NSR (4M) TKY(1T) 7523483812 (1P) \$N74LSO7NSR (4M) 03/29/04 (2P) \$N84LSO7NSR (4M) 17KY(1T) 7523483812 (2P) \$NSTATS ChipPac SCK (2P)	Title:	Title: Qualification of STATS ChipPac as an additional assembly site for selected Devices									
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TEXAS INSTRUMENTS G4 MADE IN: Malaysia 2DC: 2Q: (Q) 2000 (D) 0336 MSL 2 /260C/1 YEAR SEAL DT (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 OPT: (P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) REV: (Y) 0033317	Assem	s to prod	uct iden	tification resul	ting fro	Mo Change m this PCN: y Country Code		No Change Assembly City			
	Assem l	s to prod bly Site	uct iden	tification resul Site Origin (22L)	ting fro	Mo Change m this PCN: ly Country Code KOR		Assembly City Gwangju			

Product Affected:	
DRA829JMTGBALFR	DRA829VMTGBALFR



TI Information Selective Disclosure

Automotive New Product Qualification Summary (As per AEC-Q100 and JEDEC Guidelines)

Jacinto7- DRA829xxx and TDA4VM88xxx

Product Attributes

Attributes	Test Vehicle: DC2AAALF	Qual Device: XJ721EGALF (ES 1.0)	Qual Device: XJ721EGALF (ES 1.1)	Qual Device: XJ721EGALF (ES 1.2)
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range	-40 to +125 C	-40 to +125 C	-40 to +125 C	-40 to +125 C
Product Function	Microprocessor	Microprocessor	Microprocessor	Microprocessor
Wafer Fab Supplier	TSMC-F14	TSMC-F14	TSMC-F14	TSMC-F14
Assembly Site	SCK	SCK	SCK	SCK
Package Type	Flip Chip BGA	Flip Chip BGA	Flip Chip BGA	Flip Chip BGA
Package Designator	ALF	ALF	ALF	ALF
Ball/Lead Count	827	827	827	827

⁻ QBS: Qual By Similarity

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Spec	Min Lot Qty	SS/Lot	Test Name / Condition	Duration	Test Vehicle: DC2AAALF	Qual Device: XJ721EGALF (ES 1.0)	Qual Device: XJ721EGALF (ES 1.1)	Qual Device: XJ721EGALF (ES 1.2)
Test Group A – Accelerated Environment Stress Tests										
PC	A1	JEDEC J-STD- 020 JESD22- A113	3	77	Preconditioning	(level 3 @ 250C peak +5/-0C)	-	3/982/0		
THB	A2	JEDEC JESD22- A101	3	77	**Auto Biased Temp Humidity	85C/85%RH, (1000 Hours)	-	3/231/0		
UHST	А3	JEDEC JESD22- A102, A118, or A101	3	77	**Unbiased HAST	110C/85%RH (264 Hours)	-	3/231/0		
тс	A4	JEDEC JESD22- A104 and Appendix 3	3	77	**T/C -55C/125C	-55C/+125C (1000 Cycles)	-	3/231/0 (c)		
PTC	A5	JEDEC JESD22- A105	1	45	**Power Temperature Cycle	-40C/105C (1000 Cycles)	-	1/45/0		
HTSL	A6	JEDEC JESD22- A103	1	45	**High Temp. Storage Bake	150C (1000 Hours)	-	1/77/0 (c)		
Test Group B – Accelerated Lifetime Simulation Tests										
HTOL	B1	JEDEC JESD22- A108	3	77	HTOL - CMOS	132C Tj (1000 Hours)	-		3/231/1 (a)	
ELFR	B2	AEC Q100- 008	3	800	EFR2	135C Tj (48 Hours)	-		2/1630/0	1/811/2 (b)

⁻ Qual Device XJ721EGALF is qualified at LEVEL3-250C

					Test Group C	– Package Assembl	y Integrity Tests			
PD	C4	JEDEC JESD22- B100 and B108	3	10	Physical Dimensions (Cpk>1.67)	-	-	3/30/0	-	-
SBS	C5	AEC Q100- 010	3	50	Solder Ball Shear (Cpk>1.67)	Solder Balls		3/150/0 (BGAs)		
					Test Group D	– Die Fabrication R	teliability Tests			
EM	D1	JESD61	-	-	Electromigration	-	Comp	leted Per Process	Technology Req	uirements
TDDB	D2	JESD35	-	-	Time Dependant Dielectric Breakdown	-	Comp	leted Per Process	Technology Req	uirements
HCI	D3	JESD60 & 28	-	-	Hot Injection Carrier	-	Comp	leted Per Process	Technology Req	uirements
NBTI	D4	-	-	-	Negative Bias Temperature Instability	-	Comp	leted Per Process	Technology Requ	uirements
SM	D5	-	-	-	Stress Migration	-	Completed Per Process Technology Requirements		uirements	
Test Group E – Electrical Verification Tests										
CDM	E3	AEC Q100- 011	1	3	Auto ESD CDM	500V, 750V (corner pins)	-	-	-	1/3/0
ED	E5	AEC Q100- 009	3	30	Electrical Char.	-	-	-	-	5/90/0
Additional Tests										
BLR			-	-	BLR - Temp Cycle, -40/125C BLR TC	-40/125C (1000 cycles) (2000 cycles)	1/32/0 1/32/0	-	-	-
MQ			-	-	Manufacturability	Automotive MQ required	-	3/pass		

A1 (PC): Preconditioning:

Performed for THB, Biased HAST, AC, uHAST, TC & PTC samples, as applicable.

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40°C to +150°C Grade 1 (or Q): -40°C to +125°C Grade 2 (or T): -40°C to +105°C Grade 3 (or I): -40°C to +85°C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold: HTOL, ED

Room/Hot: THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room: AC/uHAST

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20180413-125477

Note:

- (a) 8D reports available on request.
- (b) 8D reports available on request.
- (c) Electrically Induced Physical Damage (EIPD)

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN www admin_team@list.ti.com

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